

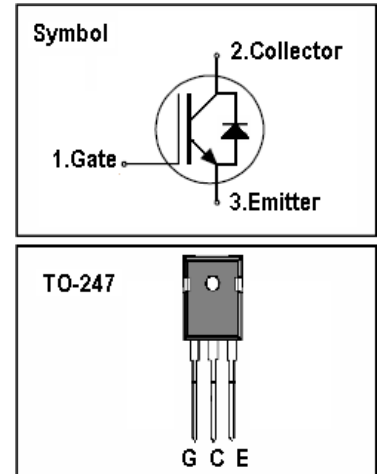
## IGBT

### Features

- 1200V, 15A
- $V_{CE(sat)(typ.)}=1.9V @ V_{GE}=15V, I_C=15A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

### General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating), UPS, general inverter and other soft switching applications.



### Absolute Maximum Ratings

| Symbol    | Parameter  | Value       | Units      |
|-----------|--|-------------|------------|
| $V_{CES}$ | Collector-Emitter Voltage                              | 1200        | V          |
| $V_{GES}$ | Gate-Emitter Voltage                                   | $\pm 30$    | V          |
| $I_C$     | Continuous Collector Current ( $T_C=25^\circ C$ )      | 30          | A          |
|           | Continuous Collector Current ( $T_C=100^\circ C$ )     | 15          | A          |
| $I_{CM}$  | Pulsed Collector Current (Note 1)                      | 45          | A          |
| $I_F$     | Diode Continuous Forward Current ( $T_C=100^\circ C$ ) | 15          | A          |
| $I_{FM}$  | Diode Maximum Forward Current (Note 1)                 | 45          | A          |
| $t_{sc}$  | Short Circuit Withstand Time                           | 10          | us         |
| $P_D$     | Maximum Power Dissipation ( $T_C=25^\circ C$ )         | 105         | W          |
|           | Maximum Power Dissipation ( $T_C=100^\circ C$ )        | 40          | W          |
| $T_J$     | Operating Junction Temperature Range                   | -40 to +155 | $^\circ C$ |
| $T_{STG}$ | Storage Temperature Range                              | -55 to +155 | $^\circ C$ |

### Thermal Characteristics

| Symbol        | Parameter                                      | Max. | Units        |
|---------------|--|------|--------------|
| $R_{th\ j-c}$ | Thermal Resistance, Junction to case for IGBT  | 1.15 | $^\circ C/W$ |
| $R_{th\ j-c}$ | Thermal Resistance, Junction to case for Diode | 1.5  | $^\circ C/W$ |
| $R_{th\ j-a}$ | Thermal Resistance, Junction to Ambient        | 40   | $^\circ C/W$ |

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

| Symbol        | Parameter                            | Test Conditions  | Min. | Typ. | Max. | Units   |
|---------------|--------------------------------------|--|------|------|------|---------|
| $BV_{CES}$    | Collector-Emitter Breakdown Voltage  | $V_{GE}=0V, I_C=250\mu A$  | 1200 | -    | -    | V       |
| $I_{CES}$     | Collector-Emitter Leakage Current    | $V_{CE}=1200V, V_{GE}=0V$  | -    | -    | 100  | $\mu A$ |
| $I_{GES}$     | Gate Leakage Current, Forward        | $V_{GE}=30V, V_{CE}=0V$  | -    | -    | 100  | nA      |
|               | Gate Leakage Current, Reverse        | $V_{GE}=-30V, V_{CE}=0V$   | -    | -    | 100  | nA      |
| $V_{GE(th)}$  | Gate Threshold Voltage               | $V_{GE}=V_{CE}, I_C=250\mu A$  | 4.5  | -    | 6.5  | V       |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $V_{GE}=15V, I_C=15A$  | -    | 1.9  | 2.4  | V       |
| $Q_g$         | Total Gate Charge                    | $V_{CC}=600V$<br>$V_{GE}=15V$<br>$I_C=15A$   | -    | 120  |      | nC      |
| $Q_{ge}$      | Gate-Emitter Charge                  |  | -    | 50   |      | nC      |
| $Q_{gc}$      | Gate-Collector Charge                |  | -    | 15   |      | nC      |
| $t_{d(on)}$   | Turn-on Delay Time                   | $V_{CC}=600V$<br>$V_{GE}=15V$<br>$I_C=15A$<br>$R_G=10\Omega$<br>Inductive Load<br>$T_C=25^\circ\text{C}$ | -    | 20   | -    | ns      |
| $t_r$         | Turn-on Rise Time                    |  | -    | 30   | -    | ns      |
| $t_{d(off)}$  | Turn-off Delay Time                  |  | -    | 150  | -    | ns      |
| $t_f$         | Turn-off Fall Time                   |  | -    | 95   | -    | ns      |
| $E_{on}$      | Turn-on Switching Loss               |  | -    | 2.8  | -    | mJ      |
| $E_{off}$     | Turn-off Switching Loss              |  | -    | 0.6  | -    | mJ      |
| $E_{ts}$      | Total Switching Loss                 |  | -    | 3.4  | -    | mJ      |
| $C_{ies}$     | Input Capacitance                    | $V_{CE}=25V$<br>$V_{GE}=0V$<br>$f=1\text{MHz}$   | -    | 2300 | -    | pF      |
| $C_{oes}$     | Output Capacitance                   |  | -    | 95   | -    | pF      |
| $C_{res}$     | Reverse Transfer Capacitance         |  | -    | 45   | -    | pF      |

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

| Symbol   | Parameter                           | Test Conditions                                    | Min. | Typ. | Max. | Units |
|----------|-------------------------------------|--|------|------|------|-------|
| $V_F$    | Diode Forward Voltage               | $I_F=15A$  | -    | 1.9  | 2.6  | V     |
| $t_{rr}$ | Diode Reverse Recovery Time         | $V_{CE}=600V$<br>$I_F=15A$<br>$dI_F/dt=200A/\mu s$ | -    | 230  |      | ns    |
| $I_{rr}$ | Diode peak Reverse Recovery Current |  | -    | 27   |      | A     |
| $Q_{rr}$ | Diode Reverse Recovery Charge       |  | -    | 1260 |      | nC    |

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

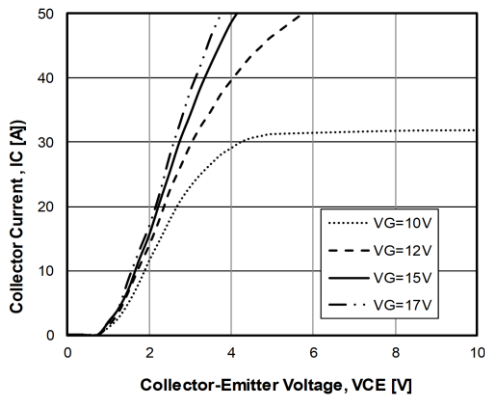


Fig 1. Output characteristics

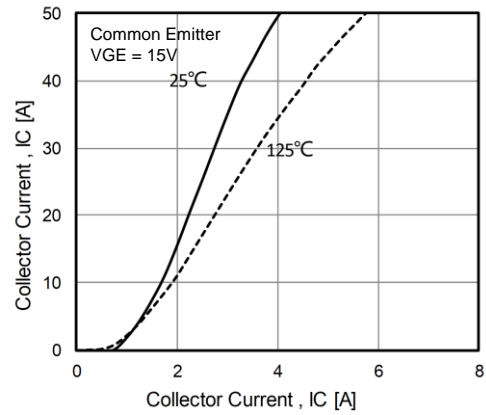


Fig 2. Typical Saturation Voltage Characteristics

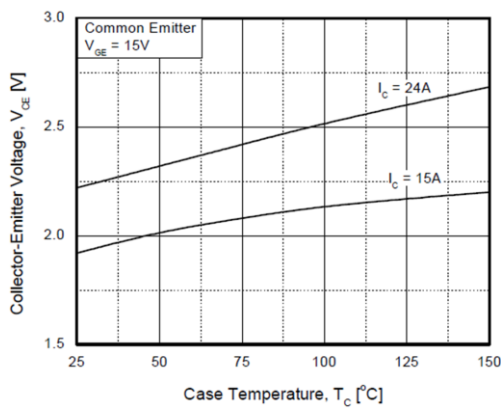


Figure 3. Saturation Voltage vs. Case Temperature at Variant Current Level

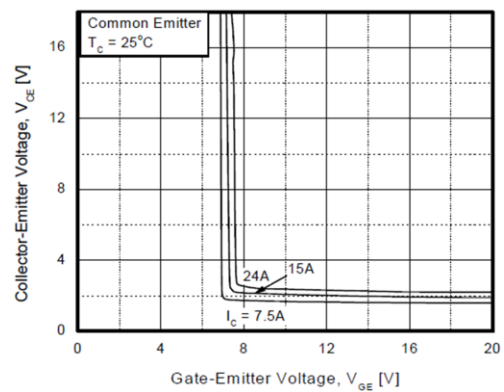


Figure 4. Saturation Voltage vs.  $V_{GE}$

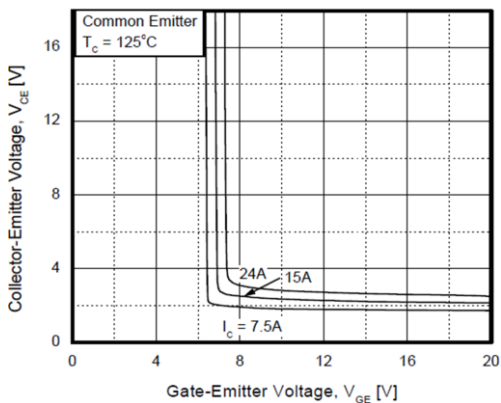


Figure 5. Saturation Voltage vs.  $V_{GE}$

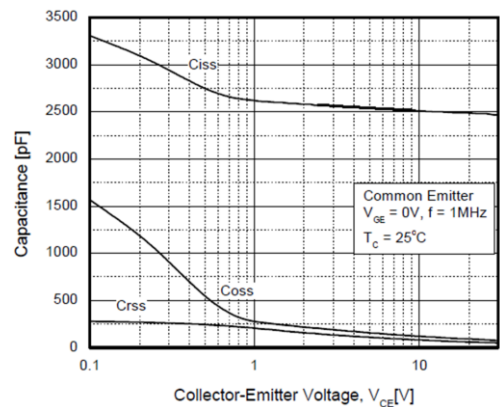


Figure 6. Capacitance Characteristics

**Typical Performance Characteristics**

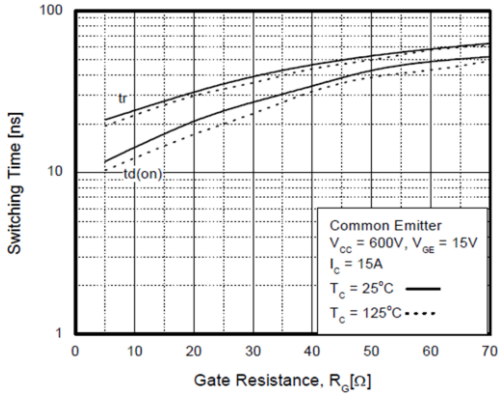


Figure 7. Turn-On Characteristics vs. Gate Resistance

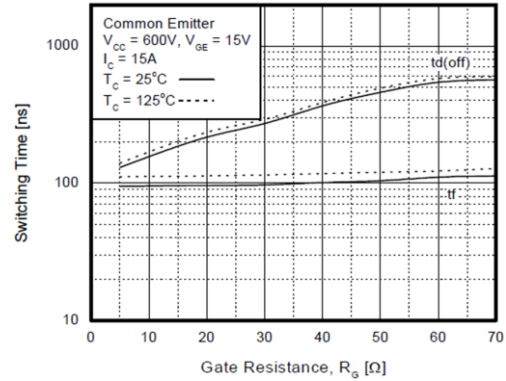


Figure 8. Turn-Off Characteristics vs. Gate Resistance

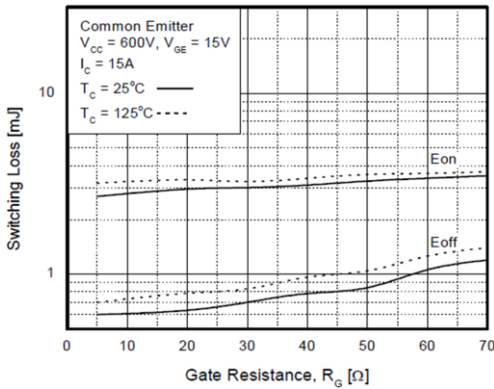


Figure 9. Switching Loss vs. Gate Resistance

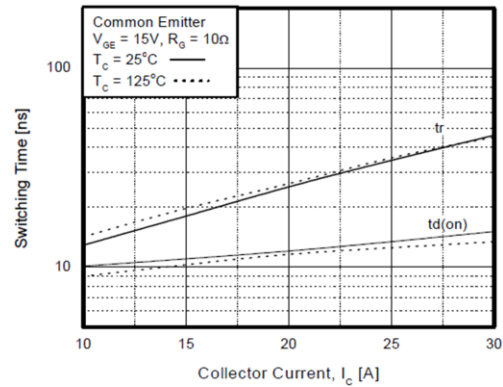


Figure 10. Turn-On Characteristics vs. Collector Current

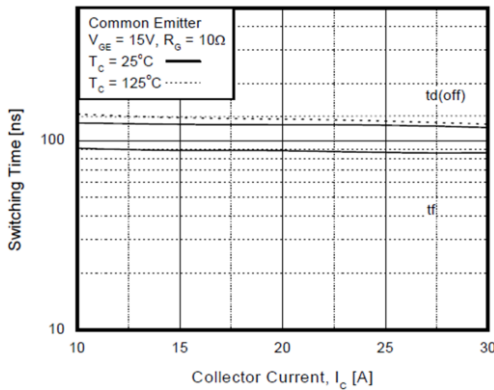


Figure 11. Turn-Off Characteristics vs. Collector Current

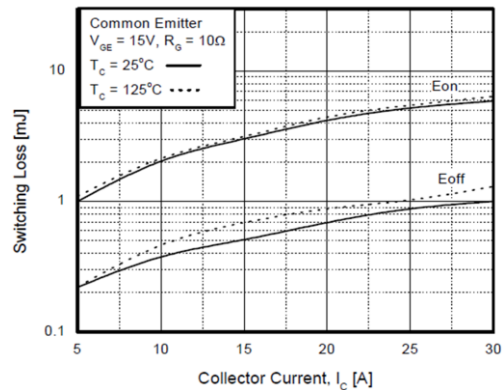


Figure 12. Switching Loss vs. Collector Current

## Typical Performance Characteristics

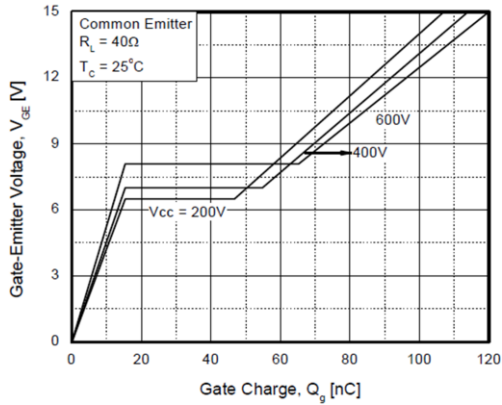


Figure 13. Gate Charge Characteristics

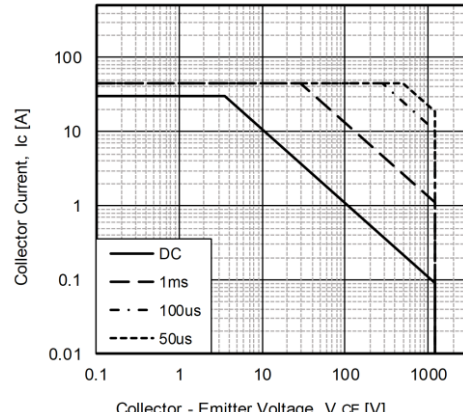


Figure 14. SOA Characteristics

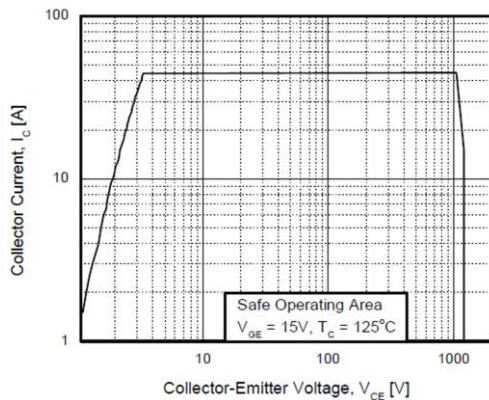


Figure 15. Turn-Off SOA

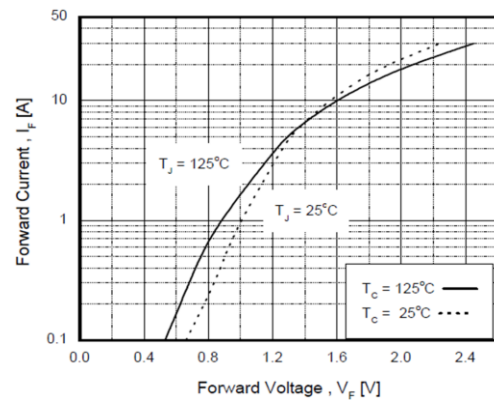


Figure 16. Forward Characteristics

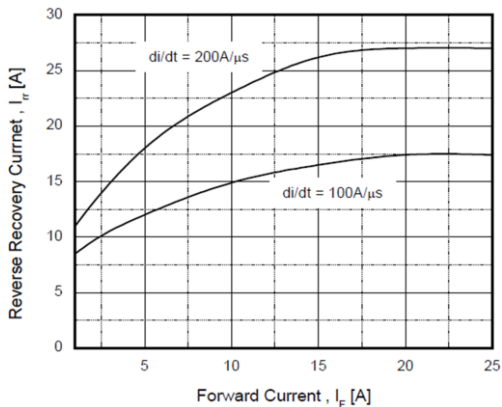


Figure 17. Reverse Recovery Current

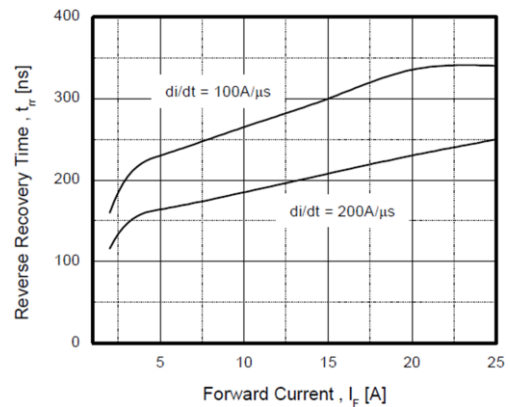


Figure 18. Reverse Recovery Time

## Typical Performance Characteristics

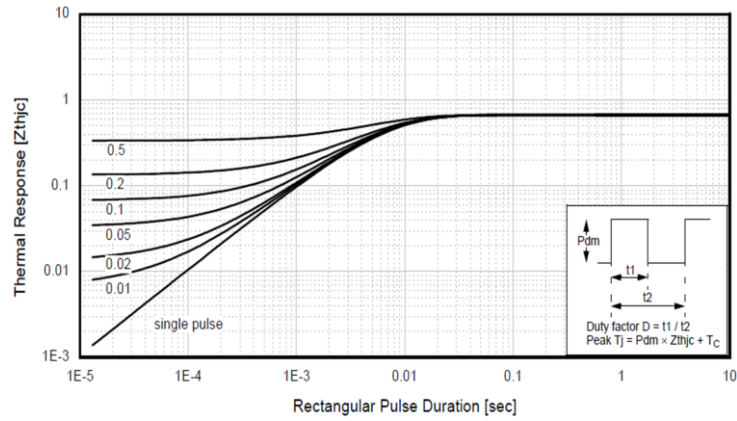
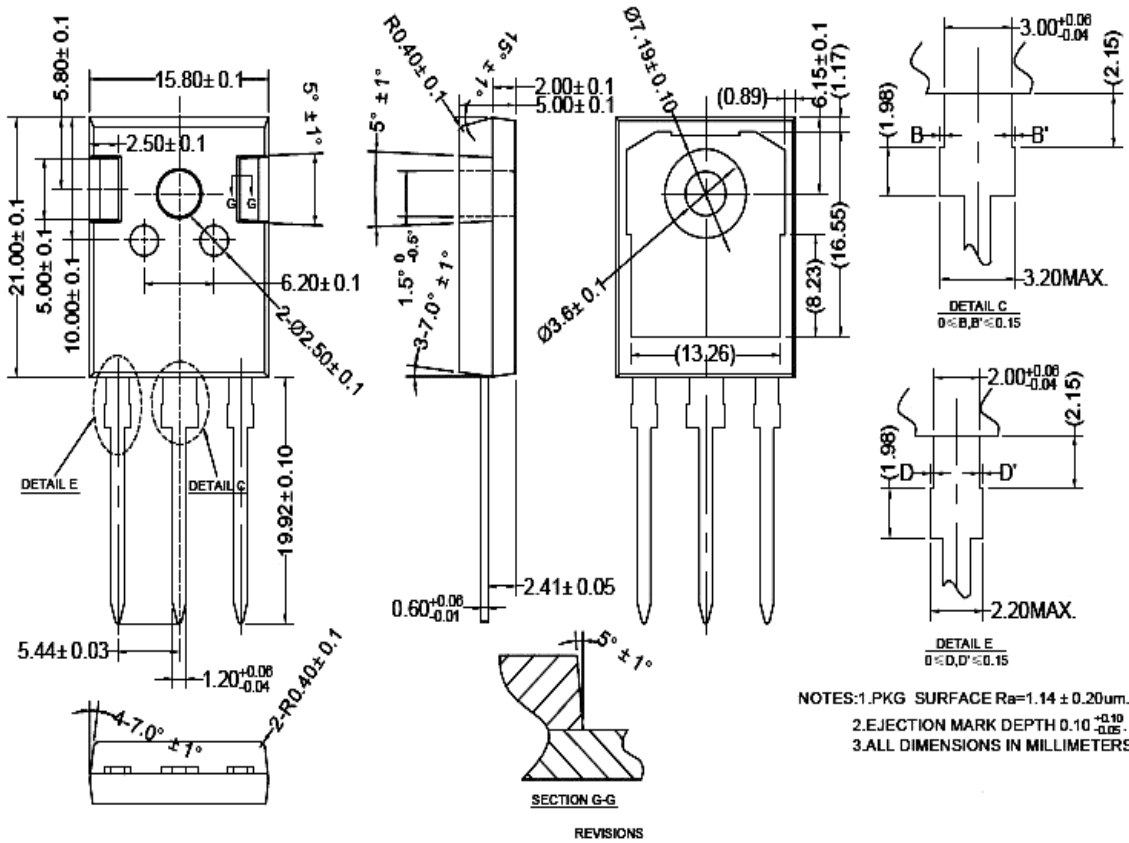


Figure 19. Transient Thermal Impedance of IGBT

## TO247 PACKAGE OUTLINE



| 公差标注   | 公差值    | 表面粗糙度     |
|--------|--------|-----------|
| 0      | ±0.2   | Ra3.2~6.3 |
| 0.0    | ±0.1   | Ra1.6~3.2 |
| 0.00   | ±0.01  | Ra0.8~1.6 |
| 0.000  | ±0.005 | Ra0.4~0.8 |
| 0.0000 | ±0.002 | Ra0.2~0.4 |

0 ≤ D, D' ≤ 0.15

NOTES: 1.PKG SURFACE Ra=1.14 ± 0.20um.  
2.EJECTION MARK DEPTH 0.10 <sup>+0.10</sup>/<sub>-0.05</sub>.  
3.ALL DIMENSIONS IN MILLIMETERS.

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